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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

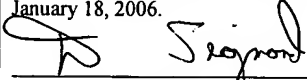
Applicant: Chuen Rong Leu et al.  
Assignee: Bridge Semiconductor Corporation  
Title: SEMICONDUCTOR CHIP ASSEMBLY WITH EMBEDDED METAL PILLAR  
Serial No.: 10/714,794 Filed: November 17, 2003  
Examiner: Williams, A. Group Art Unit: 2826  
Atty. Docket No.: BDG024

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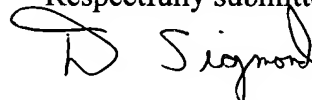
COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313

**TRANSMITTAL OF FORMAL DRAWINGS**

Attached please find the formal drawings (36 sheets) for this application.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on January 18, 2006.	
	<u>1, 18, 06</u>
David M. Sigmond Attorney for Applicant	Date of Signature

Respectfully submitted,



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